Claims

[c1] 1. A semiconductor substrate jig used for arranging a film on one surface of a semiconductor substrate, wherein said semiconductor substrate jig comprises: a frame; and an expandable member arranged within said frame, and increasing or decreasing volume while deforming a shape of said expandable member by being supplied with fluid therein; wherein said shape is deformed so that said film arranged between said semiconductor substrate and said expandable member is pressed against said semiconductor substrate as contacting portion of the expandable member to the film is enlarged outwardly from the center of said film as said volume increases.

[c2] 2. A semiconductor substrate jig as claimed in claim 1, wherein a movable plate is provided inside said expandable member, and is movable to a position contacting said expandable member when said expandable member presses substantially an entire surface of said film against said semiconductor substrate, wherein a state in which said expandable member presses said substantially entire surface of said film to said semiconductor

substrate is maintained by said movable plate.

[c3] 3. A semiconductor substrate jig claimed in claim 2, wherein a suction mechanism for suctioning said expandable member is provided in said movable plate.

[c4] 4. A semiconductor substrate jig used for arranging a film on a semiconductor substrate, wherein said semiconductor substrate jig comprises: a frame with a bottom; a set of plural annular members arranged concentrically within said frame and constructed so as to be individually movable in a direction perpendicular to said semiconductor substrate, heights of said annular members in said direction perpendicular to said semiconductor substrate gradually increases from an outer circumference toward an inner circumference; a biasing member for biasing each of said annular members toward said bottom of said frame; and an operating member contacting said annular members by operating movement in said frame and provided for biasing in a direction separating said annular members from said bottom of said frame, against bias force of said biasing member; wherein each of said annular members moves so as to gradually press and move said film arranged between said semiconductor substrate and said set of annular members toward said semiconductor substrate from center outward with said operating movement of said

operating member.

[c5] 5. A semiconductor substrate jig used in arranging a film to a semiconductor substrate, wherein said semiconductor substrate jig comprises: a frame; a porous member arranged within said frame so as to be opposite said film; and a vacuum hole formed in said frame and provided for applying negative pressure to said porous member.

[c6] 6. A semiconductor substrate jig comprising: a first jig having a first suction mechanism sucking said semiconductor substrate; and a second jig having a second suction mechanism sucking said semiconductor substrate, said first and second jigs being removably constructed and independently sucking said semiconductor substrate.